

Title (en)

INTEGRATED CIRCUITS WITH CONTACT PADS IN A STANDARD ARRAY.

Title (de)

INTEGRIERTE SCHALTUNGEN MIT ANSCHLUSSKONTAKTEN IN EINER STANDARDORDNUNG.

Title (fr)

CIRCUITS INTEGRES MUNIS DE PLOTS DE CONTACT DANS UN RESEAU STANDARD.

Publication

**EP 0179802 A1 19860507 (EN)**

Application

**EP 85901784 A 19850319**

Priority

US 59218684 A 19840322

Abstract (en)

[origin: WO8504518A1] An integrated circuit chip (310) includes a top layer of dielectric (320) penetrated by conductive vias (305) connecting electrical contacts (304) within the integrated circuit proper to a network of electrical leads (326) disposed on top of the dielectric layer (320); the network of leads (326), in turn, being connected to an array of contact pads (330) adapted for simultaneous solder connection to a leadframe.

Abstract (fr)

Une puce à circuits intégrés (310) comprend une couche supérieure de diélectrique (320) dans laquelle pénètrent des conducteurs (305) reliant les contacts électriques (304) dans le circuit intégré proprement dit à un réseau de conducteurs électriques (326) disposés au sommet de la couche diélectrique (320); le réseau de conducteurs (326) est relié à son tour à un réseau de plots de contact (330) adaptés à la connexion simultanée par soudage à un cadre conducteur.

IPC 1-7

**H01L 21/92**; **H01L 23/50**

IPC 8 full level

**H01L 21/60** (2006.01); **H01L 23/485** (2006.01); **H01L 25/16** (2006.01)

CPC (source: EP KR)

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